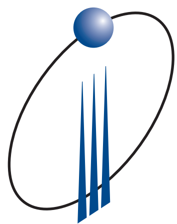


Assembly

A wide variety of standard JEDEC and custom IC packages are assembled in Class 10,000 and 1,000 clean room environments, including Open-Cavity (hermetic & non-hermetic), QFN/DFN, BGA/LGA, uBGA, CSP, Imaging Devices, COB, Med-Tech Devices, and MCM, with numerous die-attach, interconnect and seal options available.

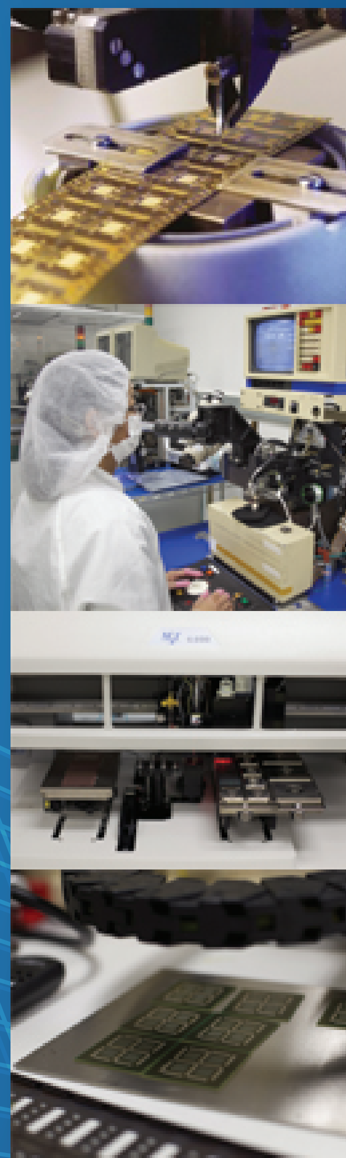
Die Attach
- Epoxy (Conductive & Non-conductive)
- DAF (Die Attach Film)
- Silver Glass
- Eutectic

Flip Chip

Wire Bonding
- Al & Au Wires
    - 0.5 mil - 2.0 mil available
    - Ultra-fine pitch

Encapsulation
- Flow cell attach
- Custom dam & fill configurations
- Plastic Molding (BGA, QFN, CSP)
- Lid Seal
- Hermetic Sealing with fine and gross leak capability

Mark & Pack
- Ink Mark
- Laser Mark
- Serialization
- Tape & Reel
- Bake & Drypack
- FGI
- Drop Ship



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